

NTMD6P02, NVMD6P02

Power MOSFET

6 A, 20 V, P-Channel SOIC-8, Dual

Features

- Ultra Low $R_{DS(on)}$
- Higher Efficiency Extending Battery Life
- Logic Level Gate Drive
- Miniature Dual SOIC-8 Surface Mount Package
- Diode Exhibits High Speed, Soft Recovery
- Avalanche Energy Specified
- These Devices are Pb-Free and are RoHS Compliant
- NVMD Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

Applications

- Power Management in Portable and Battery-Powered Products, i.e.: Cellular and Cordless Telephones, and PCMCIA Cards

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	-20	V
Gate-to-Source Voltage – Continuous	V_{GS}	± 12	V
Thermal Resistance – Junction-to-Ambient (Note 1) Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Continuous Drain Current @ $T_A = 25^\circ\text{C}$ Continuous Drain Current @ $T_A = 70^\circ\text{C}$ Maximum Operating Power Dissipation Maximum Operating Drain Current Pulsed Drain Current (Note 4)	$R_{\theta JA}$ P_D I_D I_D P_D I_D I_{DM}	62.5 2.0 -7.8 -5.7 0.5 -3.89 -40	$^\circ\text{C/W}$ W A A W A A
Thermal Resistance – Junction-to-Ambient (Note 2) Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Continuous Drain Current @ $T_A = 25^\circ\text{C}$ Continuous Drain Current @ $T_A = 70^\circ\text{C}$ Maximum Operating Power Dissipation Maximum Operating Drain Current Pulsed Drain Current (Note 4)	$R_{\theta JA}$ P_D I_D I_D P_D I_D I_{DM}	98 1.28 -6.2 -4.6 0.3 -3.01 -35	$^\circ\text{C/W}$ W A A W A A
Thermal Resistance – Junction-to-Ambient (Note 3) Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Continuous Drain Current @ $T_A = 25^\circ\text{C}$ Continuous Drain Current @ $T_A = 70^\circ\text{C}$ Maximum Operating Power Dissipation Maximum Operating Drain Current Pulsed Drain Current (Note 4)	$R_{\theta JA}$ P_D I_D I_D P_D I_D I_{DM}	166 0.75 -4.8 -3.5 0.2 -2.48 -30	$^\circ\text{C/W}$ W A A W A A
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$
Single Pulse Drain-to-Source Avalanche Energy – Starting $T_J = 25^\circ\text{C}$ ($V_{DD} = -20$ Vdc, $V_{GS} = -5.0$ Vdc, Peak $I_L = -5.0$ Apk, $L = 40$ mH, $R_G = 25$ Ω)	E_{AS}	500	mJ
Maximum Lead Temperature for Soldering Purposes for 10 seconds	T_L	260	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

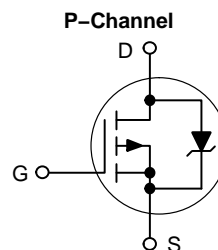
1. Mounted onto a 2" square FR-4 Board (1 in sq, 2 oz. Cu 0.06" thick single sided), $t = 10$ seconds.
2. Mounted onto a 2" square FR-4 Board (1 in sq, 2 oz. Cu 0.06" thick single sided), $t =$ steady state.
3. Minimum FR-4 or G-10 PCB, $t =$ steady state.
4. Pulse Test: Pulse Width = 300 μs , Duty Cycle = 2%.



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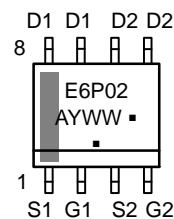
6 AMPERES, 20 VOLTS



MARKING DIAGRAM & PIN ASSIGNMENT



SOIC-8
CASE 751
STYLE 11



E6P02 = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NTMD6P02R2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
NVMD6P02R2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

NTMD6P02, NVMD6P02

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)*

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage (V _{GS} = 0 Vdc, I _D = -250 μAdc) Temperature Coefficient (Positive)	V _{(BR)DSS}	-20 -	- -11.6	- -	Vdc mV/°C
Zero Gate Voltage Drain Current (V _{DS} = -20 Vdc, V _{GS} = 0 Vdc, T _J = 25°C) (V _{DS} = -20 Vdc, V _{GS} = 0 Vdc, T _J = 70°C)	I _{DSS}	- -	- -	-1.0 -5.0	μAdc
Gate-Body Leakage Current (V _{GS} = -12 Vdc, V _{DS} = 0 Vdc)	I _{GSS}	-	-	-100	nAdc
Gate-Body Leakage Current (V _{GS} = +12 Vdc, V _{DS} = 0 Vdc)	I _{GSS}	-	-	100	nAdc

ON CHARACTERISTICS

Gate Threshold Voltage (V _{DS} = V _{GS} , I _D = -250 μAdc) Temperature Coefficient (Negative)	V _{GS(th)}	-0.6 -	-0.88 2.6	-1.20 -	Vdc mV/°C
Static Drain-to-Source On-State Resistance (V _{GS} = -4.5 Vdc, I _D = -6.2 Adc) (V _{GS} = -2.5 Vdc, I _D = -5.0 Adc) (V _{GS} = -2.5 Vdc, I _D = -3.1 Adc)	R _{DS(on)}	- - -	0.027 0.038 0.038	0.033 0.050 -	Ω
Forward Transconductance (V _{DS} = -10 Vdc, I _D = -6.2 Adc)	g _{FS}	-	15	-	Mhos

DYNAMIC CHARACTERISTICS

Input Capacitance	(V _{DS} = -16 Vdc, V _{GS} = 0 Vdc, f = 1.0 MHz)	C _{ISS}	-	1380	1700	pF
Output Capacitance		C _{OSS}	-	515	775	
Reverse Transfer Capacitance		C _{RSS}	-	250	450	

SWITCHING CHARACTERISTICS (Notes 5 and 6)

Turn-On Delay Time	(V _{DD} = -10 Vdc, I _D = -1.0 Adc, V _{GS} = -10 Vdc, R _G = 6.0 Ω)	t _{d(on)}	-	15	25	ns
Rise Time		t _r	-	20	50	
Turn-Off Delay Time		t _{d(off)}	-	85	125	
Fall Time		t _f	-	50	110	
Turn-On Delay Time	(V _{DD} = -16 Vdc, I _D = -6.2 Adc, V _{GS} = -4.5 Vdc, R _G = 6.0 Ω)	t _{d(on)}	-	17	-	ns
Rise Time		t _r	-	65	-	
Turn-Off Delay Time		t _{d(off)}	-	50	-	
Fall Time		t _f	-	80	-	
Total Gate Charge	(V _{DS} = -16 Vdc, V _{GS} = -4.5 Vdc, I _D = -6.2 Adc)	Q _{tot}	-	20	35	nC
Gate-Source Charge		Q _{gs}	-	4.0	-	
Gate-Drain Charge		Q _{gd}	-	8.0	-	

BODY-DRAIN DIODE RATINGS (Note 5)

Diode Forward On-Voltage	(I _S = -1.7 Adc, V _{GS} = 0 Vdc) (I _S = -1.7 Adc, V _{GS} = 0 Vdc, T _J = 125°C)	V _{SD}	- -	-0.80 -0.65	-1.2 -	Vdc
Diode Forward On-Voltage	(I _S = -6.2 Adc, V _{GS} = 0 Vdc) (I _S = -6.2 Adc, V _{GS} = 0 Vdc, T _J = 125°C)	V _{SD}	- -	-0.95 -0.80	- -	Vdc
Reverse Recovery Time	(I _S = -1.7 Adc, V _{GS} = 0 Vdc, dI _S /dt = 100 A/μs)	t _{rr}	-	50	80	ns
		t _a	-	20	-	
		t _r	-	30	-	
Reverse Recovery Stored Charge		Q _{RR}	-	0.04	-	μC

5. Indicates Pulse Test: Pulse Width = 300 μs max, Duty Cycle = 2%.

6. Switching characteristics are independent of operating junction temperature.

*Handling precautions to protect against electrostatic discharge are mandatory.

NTMD6P02, NVMD6P02

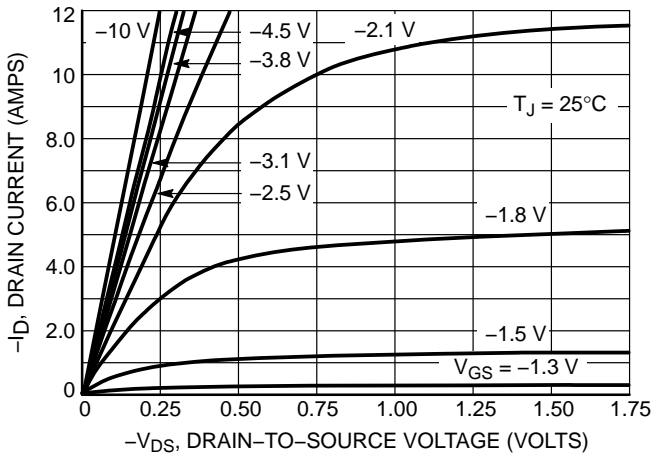


Figure 1. On-Region Characteristics

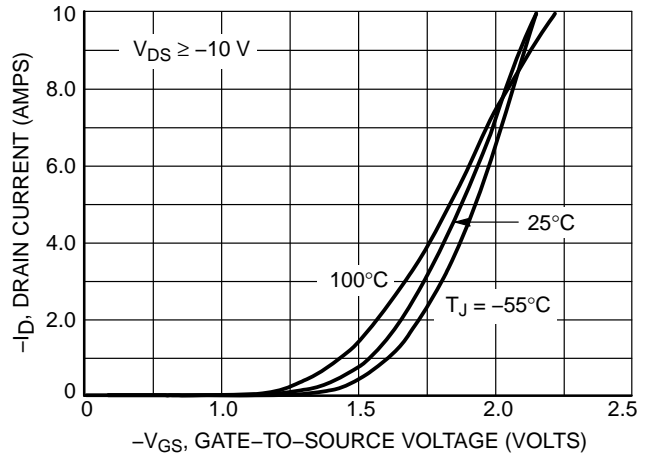


Figure 2. Transfer Characteristics

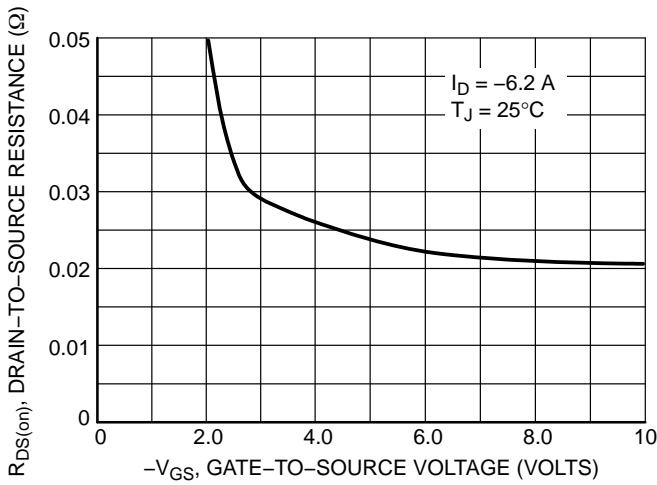


Figure 3. On-Resistance versus Gate-To-Source Voltage

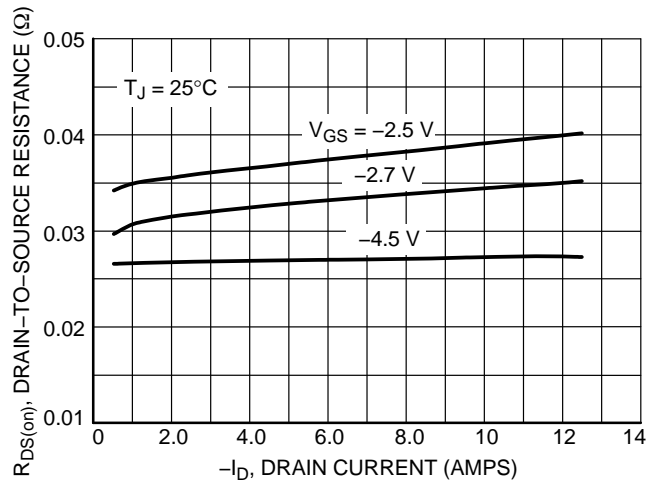


Figure 4. On-Resistance versus Drain Current and Gate Voltage

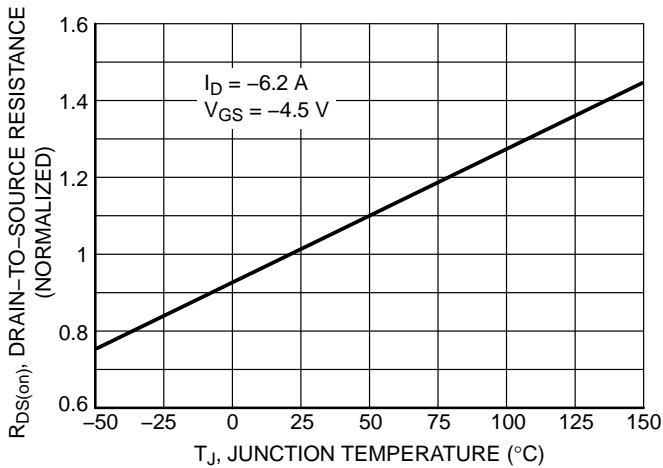


Figure 5. On-Resistance Variation with Temperature

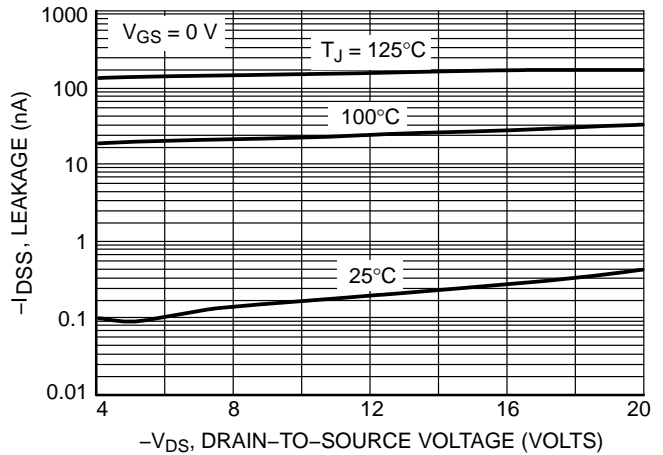


Figure 6. Drain-To-Source Leakage Current versus Voltage

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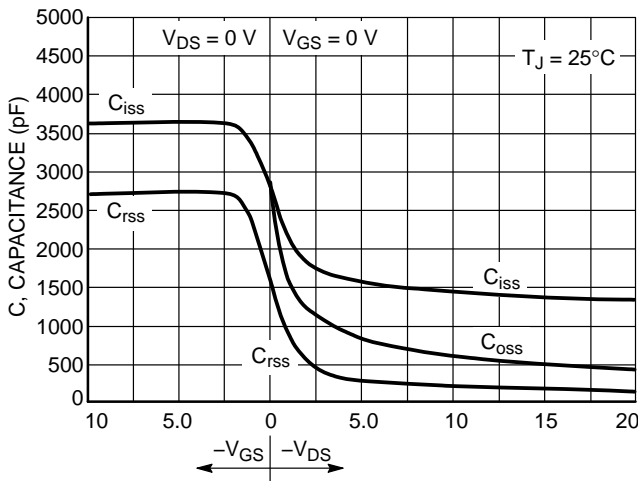


Figure 7. Capacitance Variation

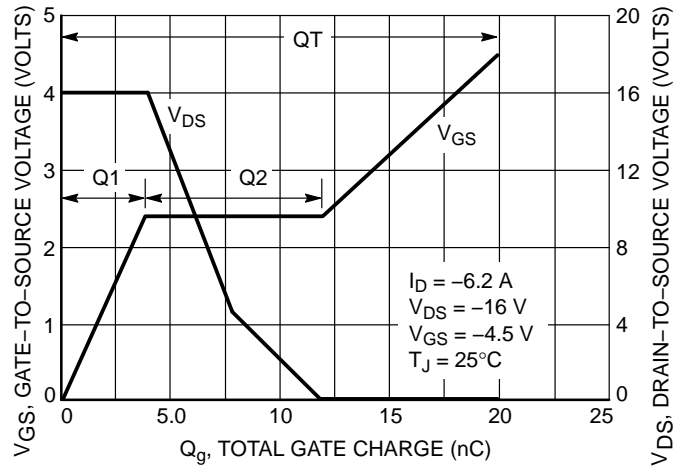


Figure 8. Gate-To-Source and Drain-To-Source Voltage versus Total Charge

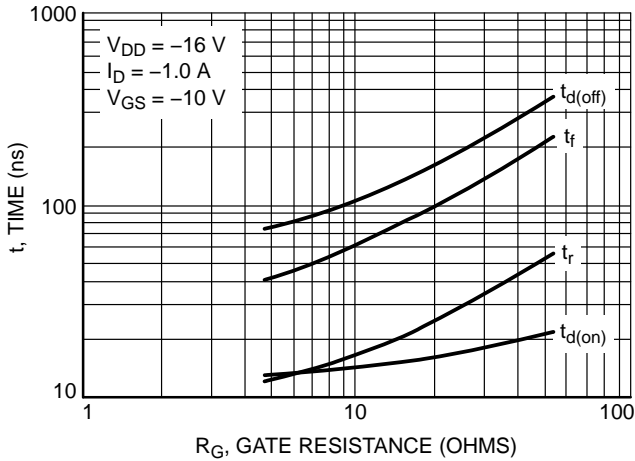


Figure 9. Resistive Switching Time Variation versus Gate Resistance

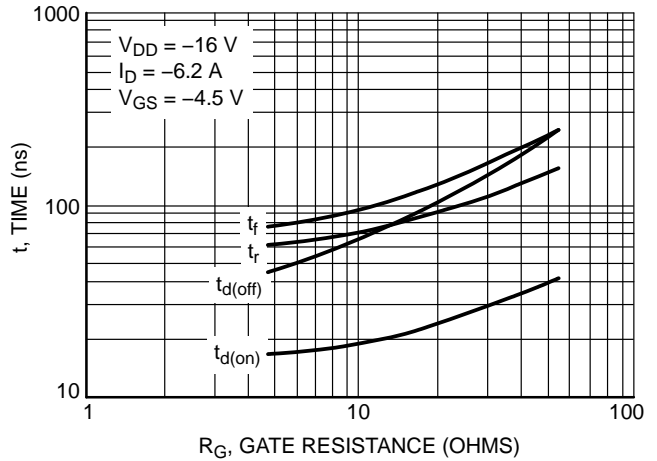


Figure 10. Resistive Switching Time Variation versus Gate Resistance

DRAIN-TO-SOURCE DIODE CHARACTERISTICS

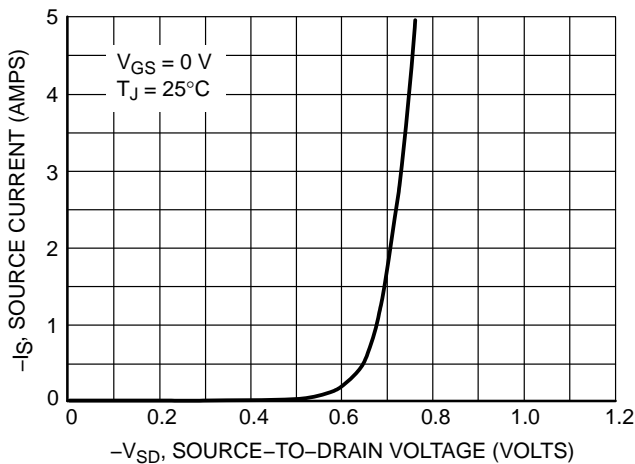


Figure 11. Diode Forward Voltage versus Current

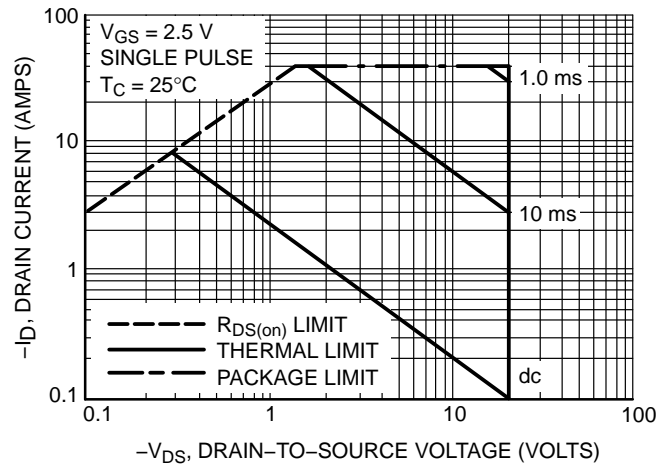


Figure 12. Maximum Rated Forward Biased Safe Operating Area

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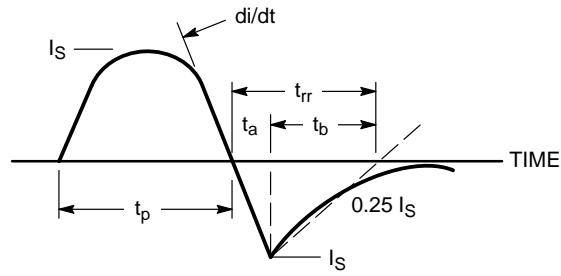


Figure 13. Diode Reverse Recovery Waveform

TYPICAL ELECTRICAL CHARACTERISTICS

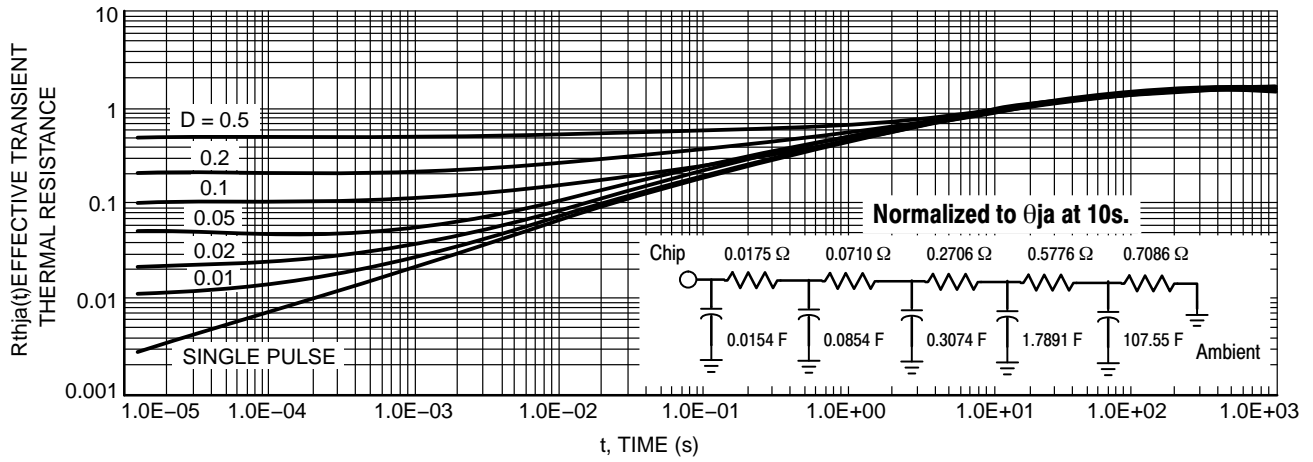
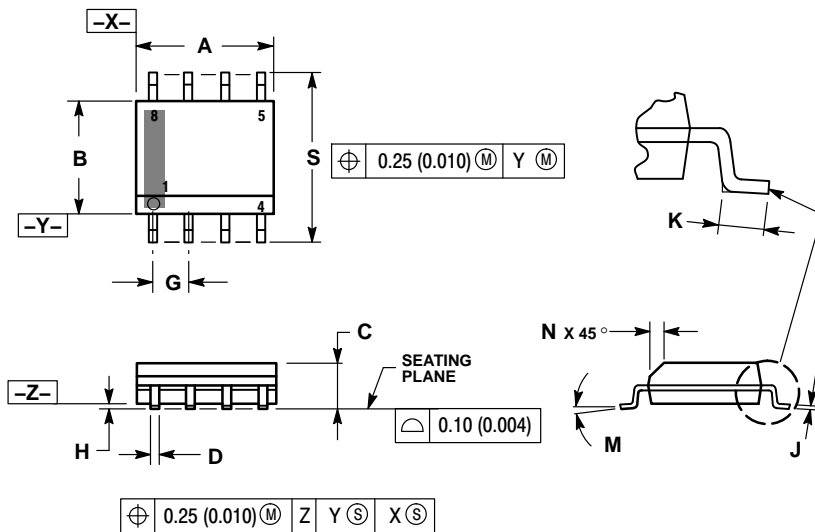


Figure 14. Thermal Response

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PACKAGE DIMENSIONS

SOIC-8 NB
CASE 751-07
ISSUE AK

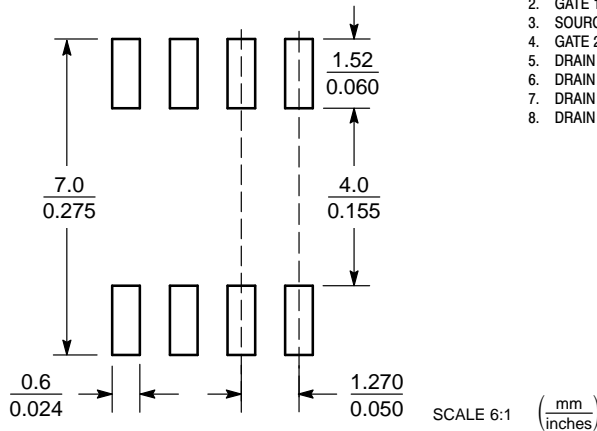


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*



STYLE 11:

1. SOURCE 1
2. GATE 1
3. SOURCE 2
4. GATE 2
5. DRAIN 2
6. DRAIN 2
7. DRAIN 1
8. DRAIN 1

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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